

Low Capacitance Dual Line ESD Protection Diode Array

SM12/SM15 SOT23-3

General Description

The SM12/SM15 of transient voltage suppressors (TVS) are designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD). TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components. The dual-junction common-anode design allows the user to protect one bidirectional data line or two unidirectional lines. The low profile SOT23-3 package allows flexibility in the design of “crowded” circuit boards. The SM12/SM15 will meet the surge requirements of IEC 61000-4-2 (Formerly IEC801-2), Level 4, “Human Body Model” for air and contact discharge.

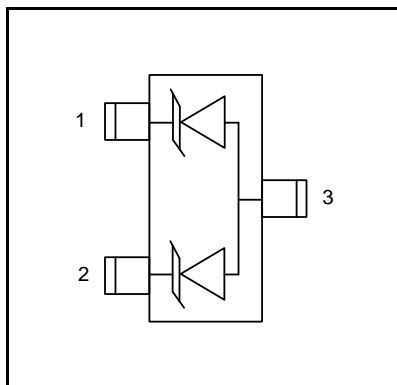
Applications

- Cellular Handsets and Accessories
- Portable Electronics
- Industrial Controls
- Set-Top Box
- Servers, Notebook and Desktop PC

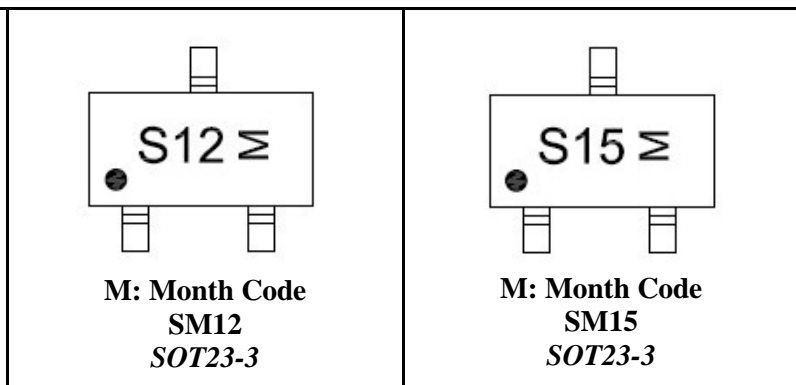
Features

- Transient Protection for Data & Power Lines to IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (Air), $\pm 8\text{kV}$ (Contact)
- Protects One Bidirectional Line or Two Unidirectional Lines
- Working Voltages: 12V (SM12)
15V (SM15)
- Low Clamping Voltage
- Solid-State Silicon Avalanche Technology

Pin Configurations



Top View



Ordering Information

| Part Number | Working Voltage | Packaging Type | Channel | Marking Code | Shipping Qty |
|-------------|-----------------|----------------|---------|--------------|------------------------------|
| SM12 | 12.0V | SOT23-3 | 2 | S12 | 3000pcs/7Inch Tape & Reel |
| SM15 | 15.0V | | | S15 | |

Absolute Maximum Ratings

| Rating | Symbol | Value | Unit |
|---|---------------|---------------|---------------|
| Peak Pulse Power ($t_p=8/20\mu s$) | P_{PK} | 140 | Watts |
| Thermal Resistance, Junction to Ambient | θ_{JA} | 325 | $^{\circ}C/W$ |
| Lead Soldering Temperature | T_L | 260 (10 sec.) | $^{\circ}C$ |
| Operating Temperature | T_J | -55 to +125 | $^{\circ}C$ |
| Storage Temperature | T_{STG} | -55 to +125 | $^{\circ}C$ |

Electrical Characteristics (SM12)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|----------------------------|---------------|--|------|------|-----|----------|
| Reverse Stand-Off Voltage | V_{RWM} | | | | 12 | V |
| Reverse Breakdown Voltage | V_{BR} | $I_T=1mA$ | 16 | | 18 | V |
| Reverse Leakage Current | I_R | $V_{RWM}=12V, T=25^{\circ}C$ | | | 1 | μA |
| Clamping Voltage | V_C | $I_{PP}=5.9A, t_p=8/20\mu s$ | | | 23 | V |
| Peak Pulse Current | I_{PP} | $t_p=8/20\mu s$ | | | 5.9 | A |
| Junction Capacitance | C_J | Pin 1 to 3 and Pin 2 to 3, $V_R=0V, f=1MHz$ | | 20 | 30 | pF |
| Reverse Dynamic Resistance | $R_{dyn,rev}$ | $I_{PP}<2A$ | | 1.12 | | Ω |
| Forward Dynamic Resistance | $R_{dyn,fwd}$ | | 0.81 | | | |
| Reverse Dynamic Resistance | $R_{dyn,rev}$ | $I_{PP}>2A$ | | 0.92 | | Ω |
| Forward Dynamic Resistance | $R_{dyn,fwd}$ | | 0.42 | | | |

Electrical Characteristics (SM15)

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|----------------------------|---------------|---|------|------|------|----------|
| Reverse Stand-Off Voltage | V_{RWM} | | | | 15 | V |
| Reverse Breakdown Voltage | V_{BR} | $I_T=1mA$ | 16.7 | | 18.7 | V |
| Reverse Leakage Current | I_R | $V_{RWM}=15V, T=25^{\circ}C$ | | | 1 | μA |
| Clamping Voltage | V_C | $I_{PP}=5.9A, t_p=8/20\mu s$ | | | 23 | V |
| Peak Pulse Current | I_{PP} | $t_p=8/20\mu s$ | | | 5.9 | A |
| Junction Capacitance | C_J | Pin 1 to 3 and Pin 2 to 3, $V_R=0V, f=1MHz$ | | 20 | 30 | pF |
| Reverse Dynamic Resistance | $R_{dyn,rev}$ | $I_{PP}<2A$ | | 1.12 | | Ω |
| Forward Dynamic Resistance | $R_{dyn,fwd}$ | | | 0.81 | | |
| Reverse Dynamic Resistance | $R_{dyn,rev}$ | $I_{PP}>2A$ | | 0.92 | | Ω |
| Forward Dynamic Resistance | $R_{dyn,fwd}$ | | | 0.42 | | |

Detailed Description
Device Connection Options

SM12/SM15 is designed to protect one bidirectional or two unidirectional data or I/O lines operating at 12V/15V. Connection options are as follows: Bidirectional: Pin 1 is connected to the data line and pin 2 is connected to ground (Since the device is symmetrical, these connections may be reversed). The ground connection should be made directly to a ground plane. The path length should be kept as short as possible to minimize parasitic inductance. Pin 3 is not connected. Unidirectional: Data lines are connected to pin 1 and pin 2. Pin 3 is connected to ground. For best results, this pin should be connected directly to a ground plane on the board. The path length should be kept as short as possible to minimize parasitic inductance.

Circuit Board Layout Recommendations for Suppression of ESD

Good circuit board layout is critical for the suppression of fast rise-time transients such as ESD. The following guidelines are recommended (Refer to application note SI99-01 for more detailed information): Place the TVS near the input terminals or connectors to restrict transient coupling. Minimize the path length between the TVS and the protected line. Minimize all conductive loops including power and ground loops. The ESD transient return path to ground should be kept as short as possible. Never run critical signals near board edges. Use ground planes whenever possible.

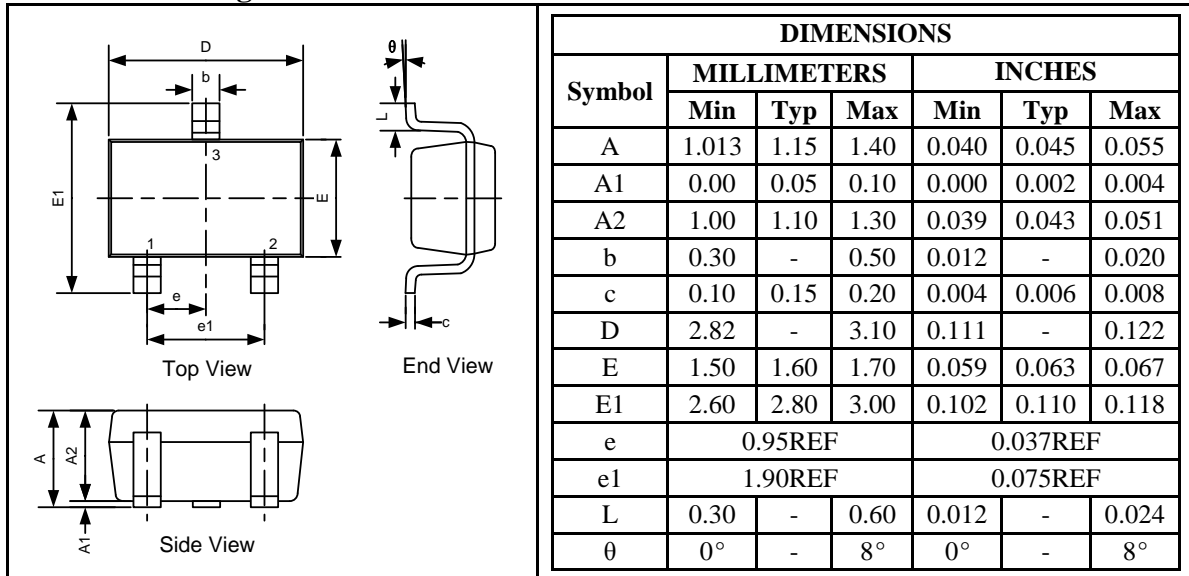
Matte Tin Lead Finish

Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. In addition, unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation of the solder joint.

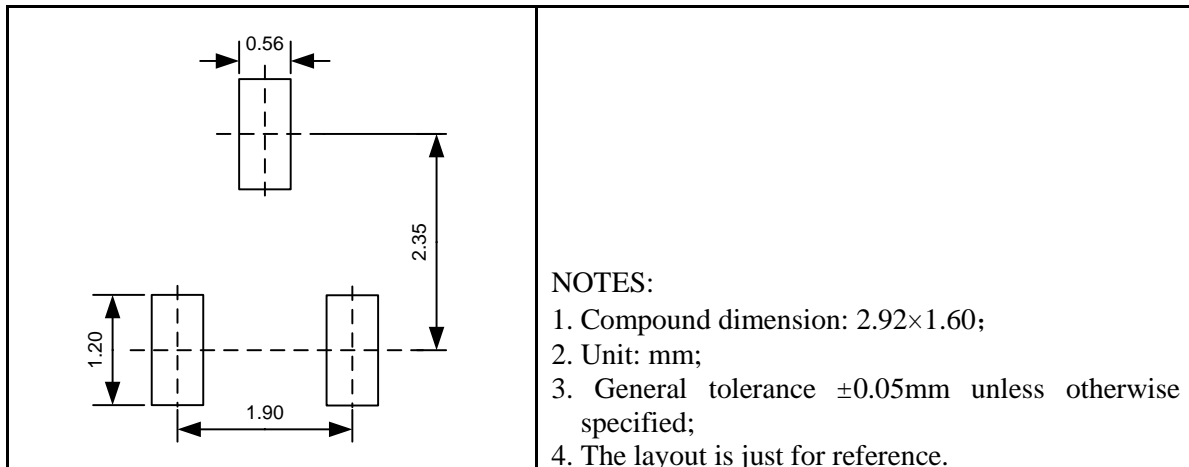
Package Information

SM12/SM15: SOT23-3

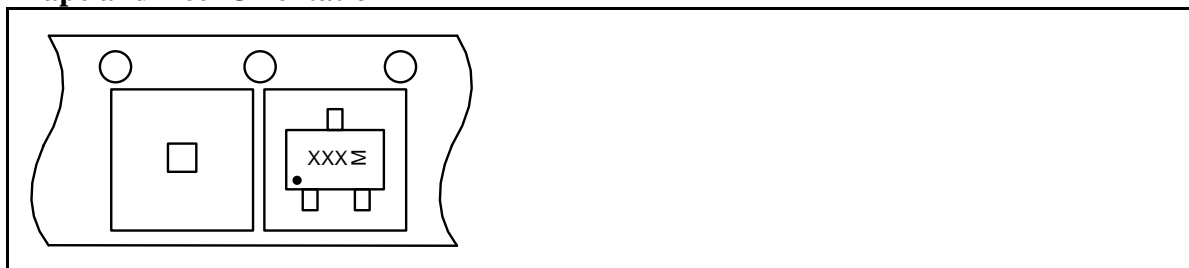
Outline Drawing



Land Pattern



Tape and Reel Orientation



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